PER-V100

CHRONTEL 7009 CHIPSET AGP BOARD

Thermal Image Analysis Report

Report No:05I080008

Release Date: 10. 25.2005

2005/10/25	*Wenyuan Yang*	*Liping Hsieh*
Issue Stamp	**Manager**	**Test Engineer**

AAEON Technology Inc.
5F, No.135, Lane 235, Pao Chiao Rd.,
Hsin-Tien City, Taipei, Taiwan, R.O.C.
TEL: +886-2-8919-1234
FAX: +886-2-8919-1056

Thermal Image Analysis

Ⅰ. Model Name: PER-V100 Rev.A0.1
HSB-835A A1.0
BIOS: HSB-835A BIOS Rev:1.2 For 7009 Chip
Backplane : BP-214 SA-P616 A1.1

Ⅱ. Description: CHRONTEL 7009 CHIPSET AGP BOARD

Ⅲ. Date: 10.25.2005

Ⅳ. Measure Site: AAEON QE Dept.

Ⅴ. Issued by : Liping Hsieh

Ⅵ.Equipment:

1. TVS-100 series by NIPPON AVIONICS CO., LTD.

Ⅶ. Simulation Environment:

- **Temperature: Component Side : 26.0℃**
  Solder Side : N/A
- **CPU: Intel / Pentium 4 CPU 2.0GHz/400**
- **RAM: SAMSUNG /K4H560438E-GCCC / DDR400 /512MB**
- **CF Card: N/A**
- **Application Software: Run HCT System Stress Test under Win2000 Professional**
- **Take Picture Time: After Power on 2 hours.**

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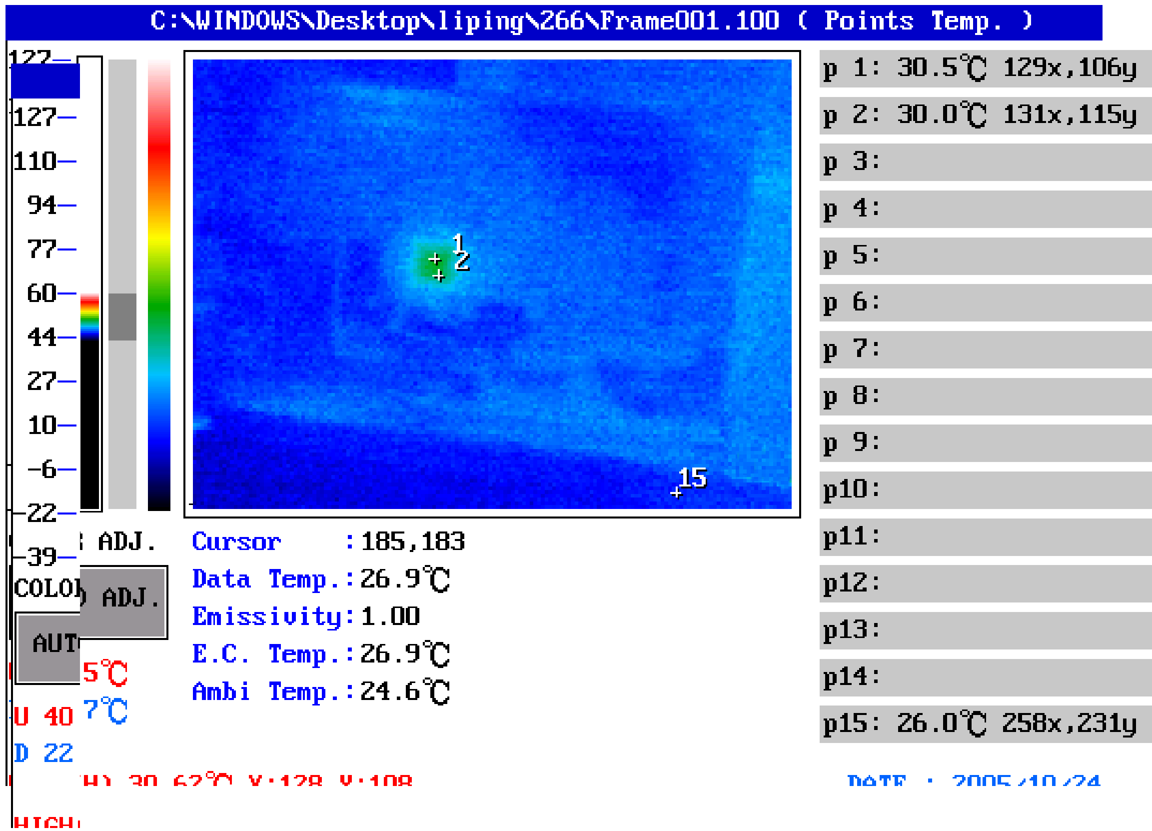
Temperature Profile Test:

Component Side



Point	Position	Describe	Tc (℃)	Tm (25℃)	Tm (60℃)	Note
1	U3	CHRONTELINC/CH7009A/IC.SMDLQFP.64PDVI/TV ENCODER.CHRONTEL.CH7009A;	125℃	30.5℃	65.5℃	
2	Y2	X TAL.DIP.14.318MHz.2P.16pf/30ppm.	-20℃~70℃	30.0℃	65℃	
3						
4						
5						
6						
7						
8						
9						
10						
11						
12						
13						
14						
15				26.0℃		

1. Operation Temperature (℃):
Tc(Case Temp.) = Ta(Ambient Temp.)+/-30℃ = Tj(Junction Temp.)-/+25℃

Note: The description in red states which temperature is over the specification of the device.

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